

FORM 2

THE PATENTS ACT, 1970
(39 of 1970)
AND
THE PATENTS RULES, 2003

**COMPLETE
SPECIFICATION**

(See Section 10; rule 13)

TITLE OF THE INVENTION

“CURABLE COMPOSITIONS”

APPLICANT

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The following specification particularly describes
the invention and the manner in which
it is to be performed

Claims

What is claimed:

1. A curable composition comprising:
 - an epoxy resin;
 - a hardener selected from the group consisting an anhydride, an amine, a phenolic, and combinations thereof; and
 - a block copolymer having a thermoset-philic block and a thermoset-phobic block, wherein the block copolymer is from 35 weight percent to 80 weight percent of the curable composition, the thermoset-philic block includes constitutional units that are derived from an alkylene oxide monomer, and the thermoset-phobic block includes constitutional units that are derived from an alkylene oxide monomer.
2. The curable composition of claim 1, wherein the alkylene oxide monomer that constitutional units of the thermoset-philic block are derived from has from two to three carbon atoms.
3. The curable composition of any one of the preceding claims, wherein the alkylene oxide monomer that constitutional units of the thermoset-phobic block are derived from has from four to twenty carbon atoms.
4. The curable composition of any one of the preceding claims, wherein the thermoset-philic block includes constitutional units that are derived from an alkylene oxide monomer having two carbon atoms and the thermoset-phobic block includes constitutional units that are derived from an alkylene oxide monomer having four carbon atoms.
5. The curable composition of any one of the preceding claims, wherein the block copolymer has a number average molecular weight in a range from 1000 to 50000.

6. The curable composition of any one of the preceding claims, wherein the block copolymer is a diblock copolymer.
7. The curable composition of any one of claims 1-5, wherein the block copolymer is a multiblock copolymer.
8. The curable composition of any one of the preceding claims, wherein the epoxy resin is selected from the group consisting of an aromatic epoxy resin, an alicyclic epoxy resin, an aliphatic epoxy resin, and combinations thereof.
9. The curable composition of any one of the preceding claims, wherein the hardener is selected from the group consisting of hexahydrophthalic anhydride, methyltetrahydrophthalic anhydride, methylhexahydrophthalic anhydride, methylnadic anhydride, methylbutenyltetrahydrophthalic anhydride, and combinations thereof.
10. A product obtained by curing the curable composition as in any one of the preceding claims.

dated this 06 day of May 2014.

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